



Thermal Pad KB5100S

Thermal pads are used to fill the air gap between a heat generating device and a heat sink or metal base. Their flexible and elastic characteristics enable them to be used to cover very uneven surfaces. Heat is conducted from a separate device or the entire PCB to a metal housing or diffusion plate, thereby increasing the efficiency and service life of the heat generating electronic components.

Performance parameter table






Series	color	Thermal Conductivity (W/m*K)	Hardness (Shore 00)	Thickness (mm)	Density (g/cm ³)	Dielectric strength (KV/mm)	Fire Rating	Volume Resistivity ($\Omega \cdot \text{cm}$)
KB5110S	custom made	1.0±0.5	40~70	0.5--5.0	2.60±0.05	≥12	UL94- V 0	≥10 ¹³
KB5120S	custom made	2.0±0.5	40~70	0.5--5.0	2.83±0.05	≥12	UL94- V 0	≥10 ¹³
KB5130S	custom made	3.0±0.5	40~70	0.5--5.0	3.05±0.05	≥12	UL94- V 0	≥10 ¹³
KB5140S	custom made	4.0±0.5	40~70	0.5--5.0	3.23±0.05	≥12	UL94- V 0	≥10 ¹³
KB5150S	custom made	5.0±0.5	40~70	1.0--5.0	3.40±0.05	≥12	UL94- V 0	≥10 ¹³



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The structure diagram is as follows

序号/NO	材料 /Layer & Material		备注/Remark
1	Structure		Base film 50 um Released film
2			Glue Acylic B side
3			Base material 25 um Released film
4			Glue Silicone foam B side
5			Bottom film Fluorine release film

Specific features:

1. The tape is self-adhesive and does not require additional surface adhesives and adhesive backing. It has good elasticity and recovery and can adapt to pressure changes and temperature fluctuations.
2. It has good heat conduction effect, effectively protecting the life and safety of the working body
3. Different thickness and size options can be provided according to actual application
4. Good processing performance, easy installation and pressing, no adhesion to the sealing surface, easy to disassemble
5. Low hardness, good compliance, low stress, more effective protection of electrical components
6. Excellent high and low temperature resistance, chemical and mechanical stability, weather resistance, radiation resistance and dielectric properties
7. Applicable to all electronic, medical, battery, mobile phone, computer and other industries that require heat dissipation, such as computer storage chips , display driver IC , CD-ROM/DVD , LCD TV backlight unit , communication equipment between CPU and radiator , etc.

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